

ABSTRACT OF THE DISCLOSURE

A plurality of IPs can be mounted as chip IPs on a silicon wiring substrate. The silicon wiring substrate includes a plurality of wires. The IPs (chip IPs) are attached to and mounted on pads that are connected to the wires of the silicon wiring substrate. Test pads are provided on the silicon wiring substrate so as to be connected to wires that are connected to a power supply line, a ground line and an internal circuit in each IP. The condition of the connection between the IPs and the silicon wiring substrate is determined based on the fact that a forward current flows through a protection diode when a voltage of the opposite polarity is applied to the power supply line or the ground line. A test circuit for testing an electrical connection may be provided in each chip IP.